

PRODUCT NO

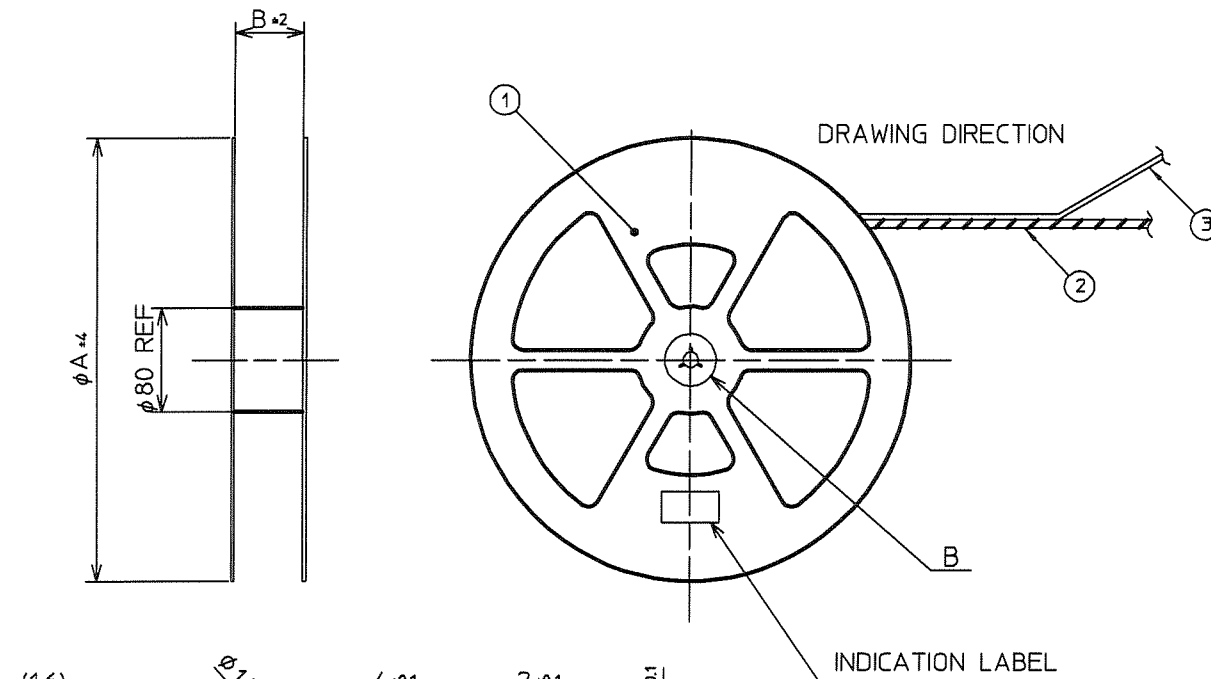
10061122-**-1**0*LF

EMBOSS TAPE

DIMENSIONS

	φ A	B	C
10061122-131**0*LF~451**0*LF	φ330	25.5	24
10061122-511**0*LF~		33.5	32

PT.NO.	PARTS NAME	PRODUCT NO.	MATERIAL	Q'TY	NOTE
1	REEL		POLYSTYRENE	1	COLOR:WHITE,ELECTRIFICATION PREVENTION PROCESSING
2	EMBOSS TAPE		PP OR PET	1	ELECTRIFICATION PREVENTION PROCESSING
3	COVER TAPE		POLYESTER		
4	CONNECTOR	10061122 -**-1**1LF	10061122 SHEET2,3	5000	
		10061122 -**-1**HLF	10061122 SHEET4,5 6,7		



ADHESIVE TAPE

DRAWING DIRECTION
400MIN
COVER TAPE
LEADER PORTIONCONNECTOR PACKAGING
PORTION30 HOLES MIN
(EMPTY)20 HOLES MIN
(EMPTY)

CONNECTOR PACKAGING CONDITION

NOTE

- 1.THIS ARTICLE CARRIES OUT THE EMBOSS TAPE PACKAGE OF THE P/N10061122 SERIES CONNECTOR
- 2.THE SHAPE AND DIMENSION OF THIS ARTICLE ARE BASED ON JIS C 0806 (TAPING OF ELECTRONIC PARTS(SURFACE MOUNTED DEVICE))

P/N COMPOSITION

▷10061122-**-1**0*LF

HOUSING MATERIAL 1E:NONE-HALOGEN FREE RESIN
2H:HALOGEN FREE RESIN

LEAD FREE

PACKAGING FORM (E:PLASTIC REEL/EMBOSS TAPE PACKAGE)

EMBOSSING TAPE PACKAGE 0: 8mm PITCH

PLATING SPEC 1:AU PLATING

MOUNTING 1:SMT/WITH CABLE LOCK

2:SMT/WITHOUT CABLE LOCK

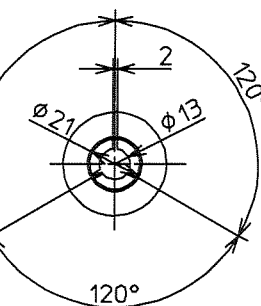
▷3:SMT/WITH CABLE LOCK/WITH ACTUATOR LOCK

▷4:SMT/WITHOUT CABLE LOCK/WITH ACTUATOR LOCK

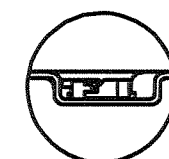
CONTACT SIDE 1:DOWN SIDE

NO OF POSITION

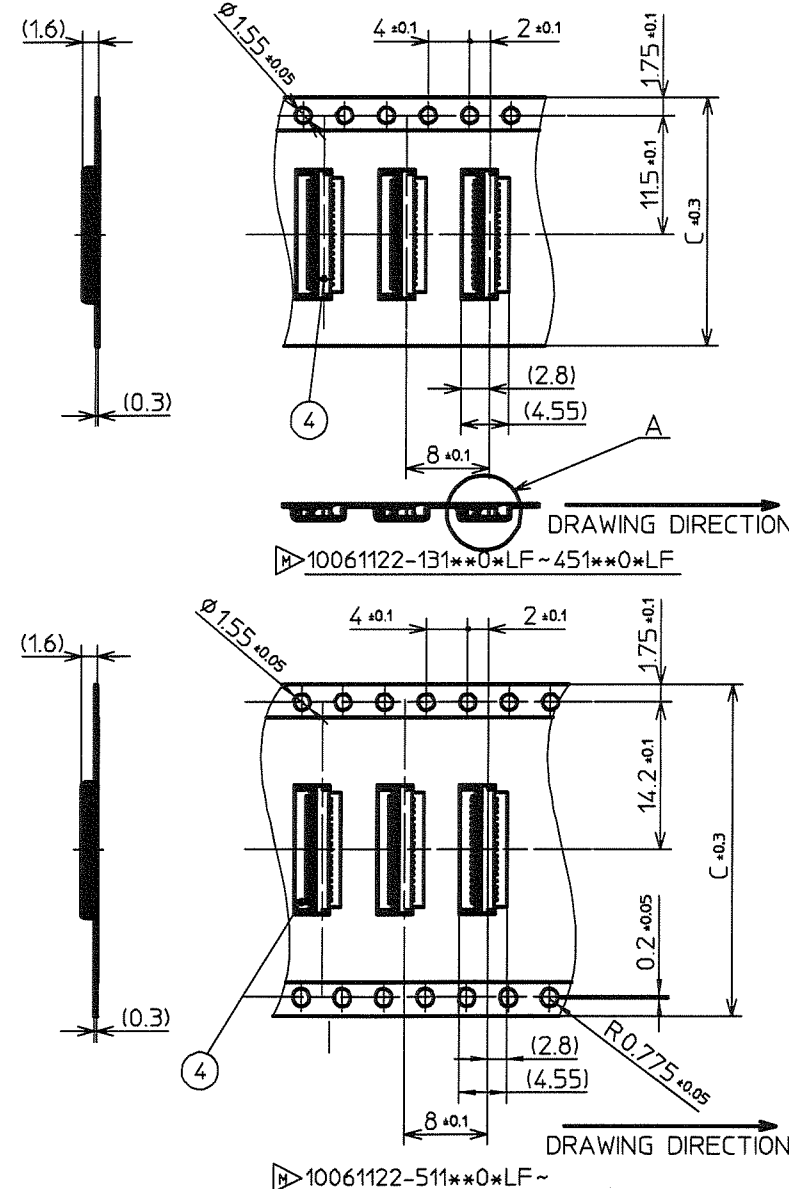
SERIES NAME



DETAIL B

Actuator is close
Initial condition

DETAIL A

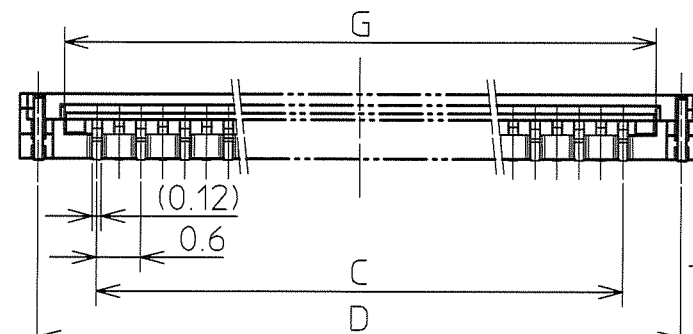
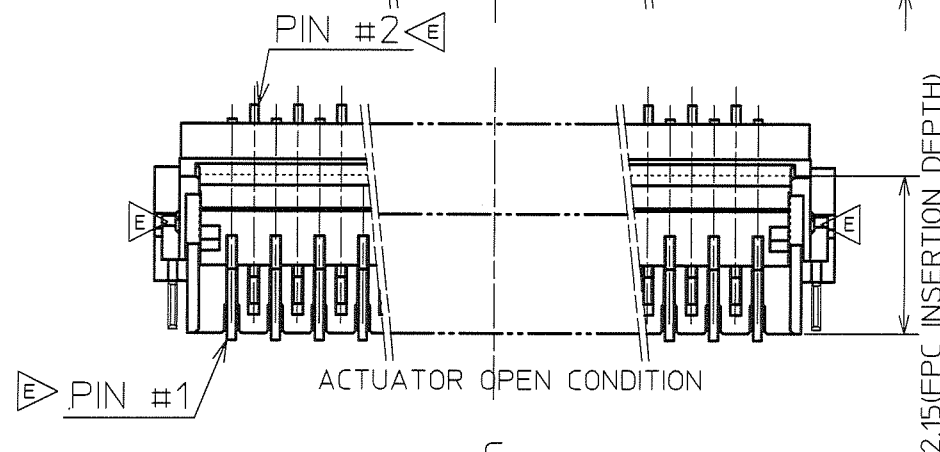
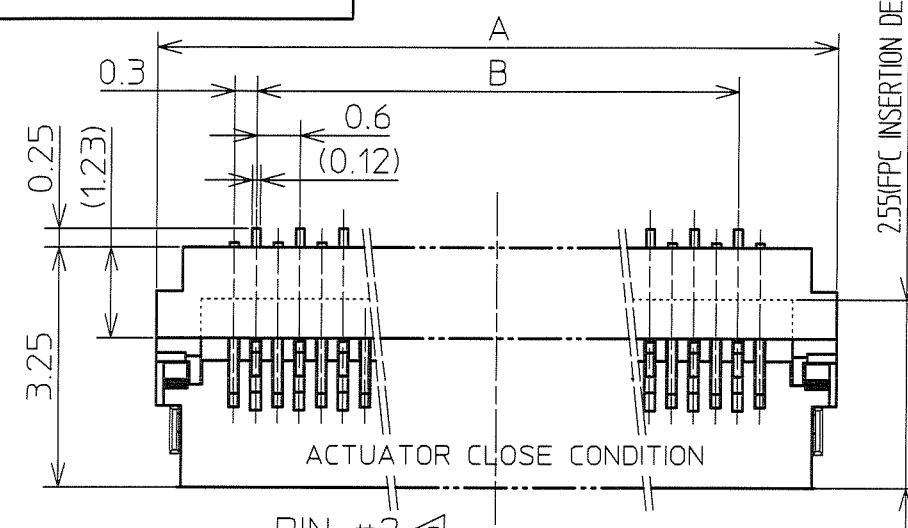


▷10061122-131**0*LF~451**0*LF

▷10061122-511**0*LF~

mat'l. code				surface		tolerance		projection		product family		CODE	
lir	description	ecn no	dr	date	ISO 1302	ISO 406	ISO 1101	MM	scale	587F (YLL-D)	JP	file	
G	REVISED	J07-0399	K.O	28/Sep/07	angles		± 0.3					0.3mm PITCH FPC CONNECTOR	
F	REVISED	J07-0130	K.O	23/Feb/07	linear							DOWN CONTACT TYPE ET PACKAGING	
E	REVISED	J06-0483	K.O	17/Nov/06									
N	REVISED	J10-0268	T.I	2010-10-12								dwg no	sheet of size
M	REVISED	J10-0185	T.I	2010-7-4								10061122	▷10F37 A2
L	REVISED	J10-0073	T.I	2010-5-17								type	Product Customer Drawing
K	REVISED	J08-0430	K.O	2008-11-10									
J	REVISED	J08-0315	K.O	2008-7-28									
H	REVISED	J08-0189	K.O	2008-4-28									
sheet index				revision	N	L	E	A	A	B	A		Rev. N
				sheet	1	2	3	4	5	6	7		

10061122-**-111LF




NOTE

1.MATERIAL

1)HOUSING:THERMOPLASTIC RESIN,UL94V-0,NATURAL
2)ACTUATOR:THERMOPLASTIC RESIN,UL94V-0,BLACK
3)CONTACT:COPPER ALLOY
4)FIXING TAB:COPPER ALLOY

2.FINISH

1)CONTACT:ALL OVER Ni (WITH Ni BARRIER) 
(CONTACT AREA)Au
(SOLDER TAIL AREA)Au

2)FIXING TAB:ALL OVER NI

Sn PLATING

3.CO-PLANARITY:~~0.04MAX~~ 0.08MAX

4. THICKNESS OF A METAL MASK: 0.1 μm

5. FPC

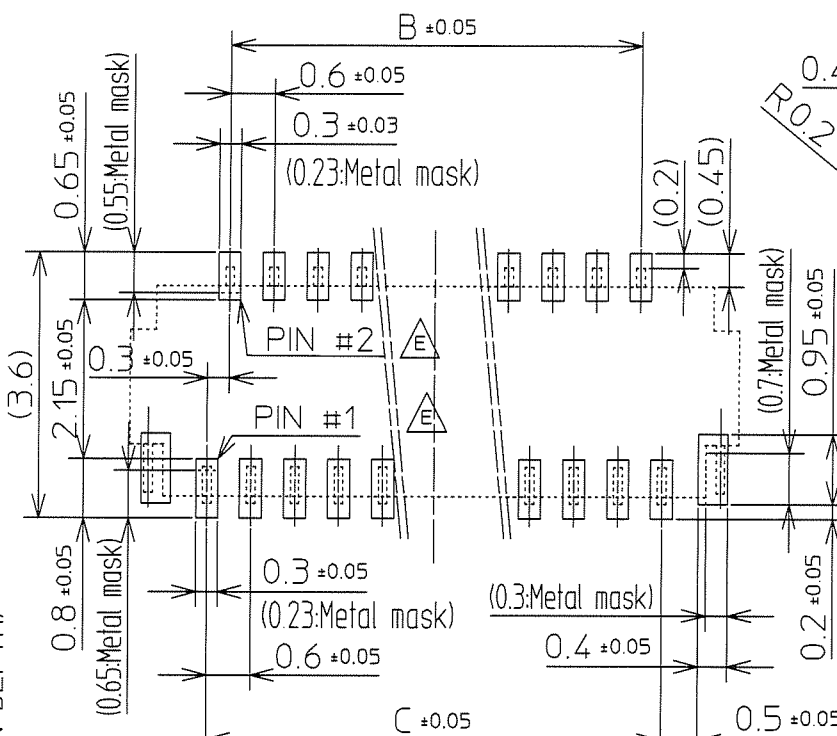
ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.

6.PRODUCT

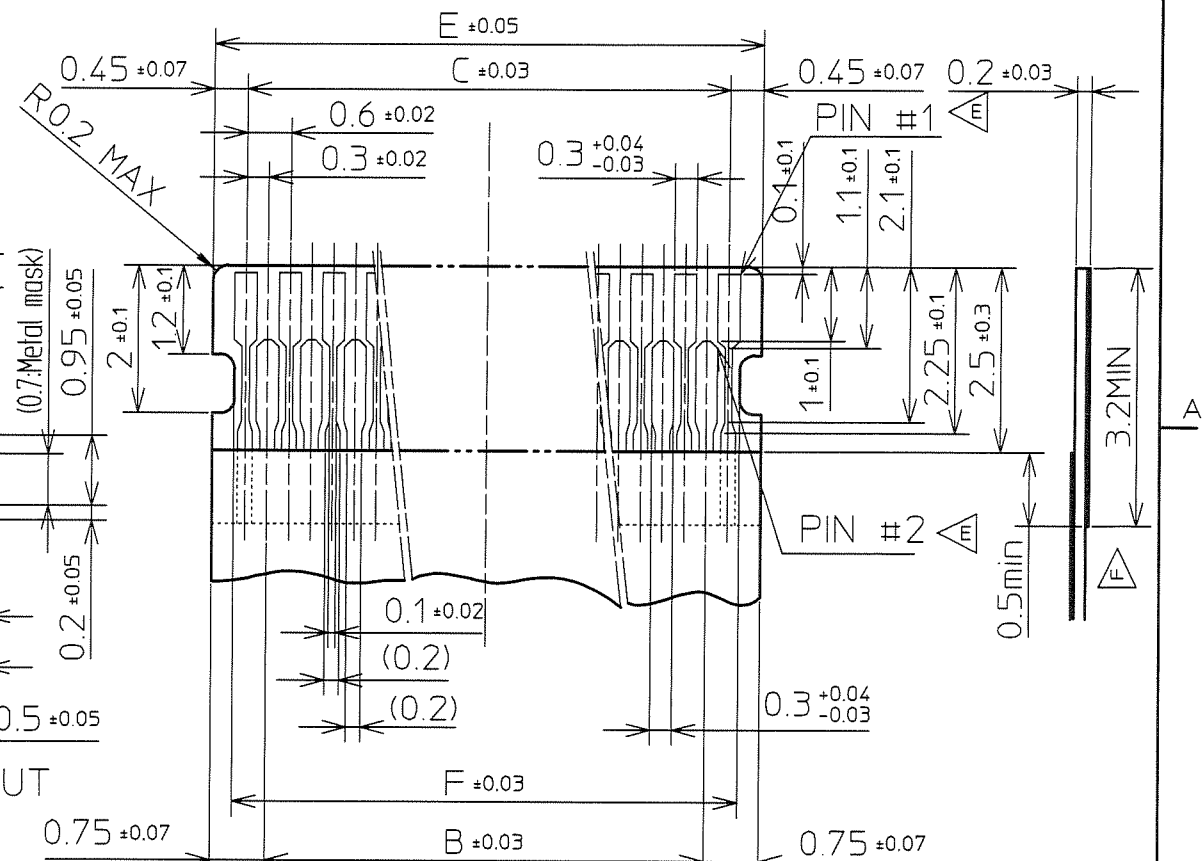
RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS
10064555-**2110ELF(YLL-UPPER CONTACT TYPE)

7.0 OTHER

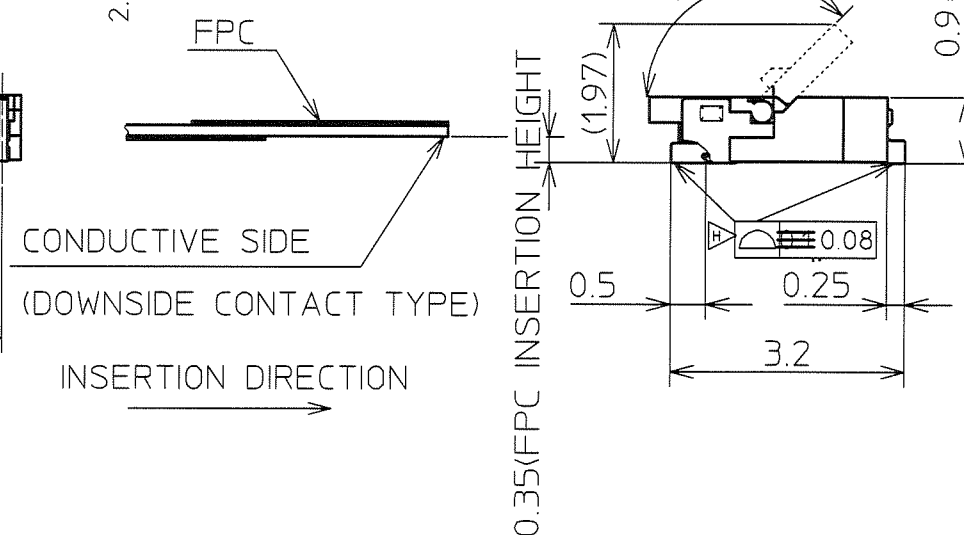
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008



RECOMMENDED PC BOARD LAYOUT



RECOMMENDED FPC CONFIGURATION



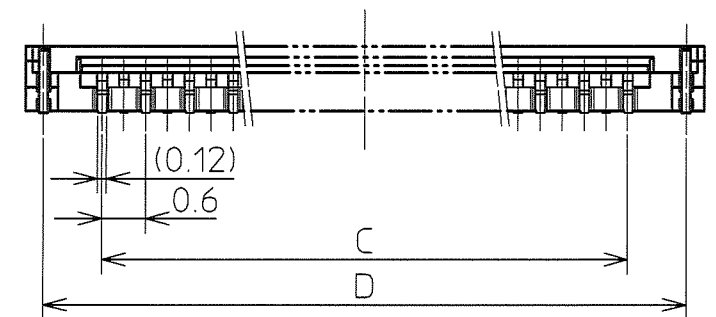
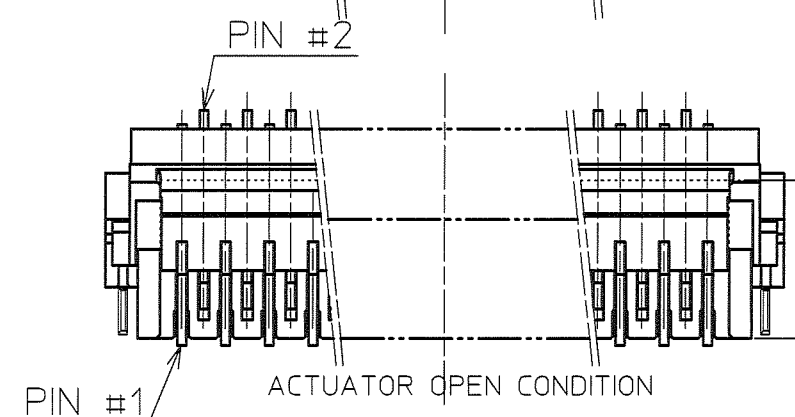
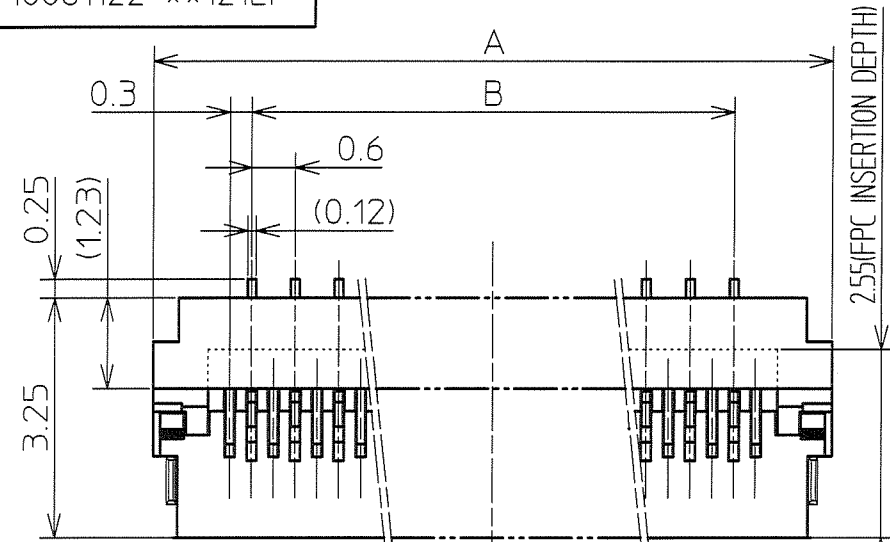
	P/N	A	B	C	D	E	F	G
▶	10061122-13111LF	5.7	3.0	3.6	5.2	4.5	3.9	4.53
▶	10061122-15111LF	6.3	3.6	4.2	5.8	5.1	4.5	5.13
▶	10061122-17111LF	6.9	4.2	4.8	6.4	5.7	5.1	5.73
▶	10061122-21111LF	8.1	5.4	6.0	7.6	6.9	6.3	6.93
	10061122-23111LF	8.7	6.0	6.6	8.2	7.5	6.9	7.53
	10061122-25111LF	9.3	6.6	7.2	8.8	8.1	7.5	8.13
	10061122-33111LF	11.7	9.0	9.6	11.2	10.5	9.9	10.53
	10061122-35111LF	12.3	9.6	10.2	11.8	11.1	10.5	11.13
	10061122-39111LF	13.5	10.8	11.4	13.0	12.3	11.7	12.33
	10061122-41111LF	14.1	11.4	12.0	13.6	12.9	12.3	12.93

[illegible]

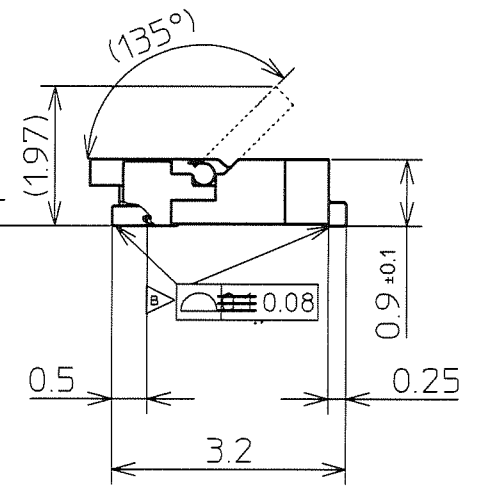
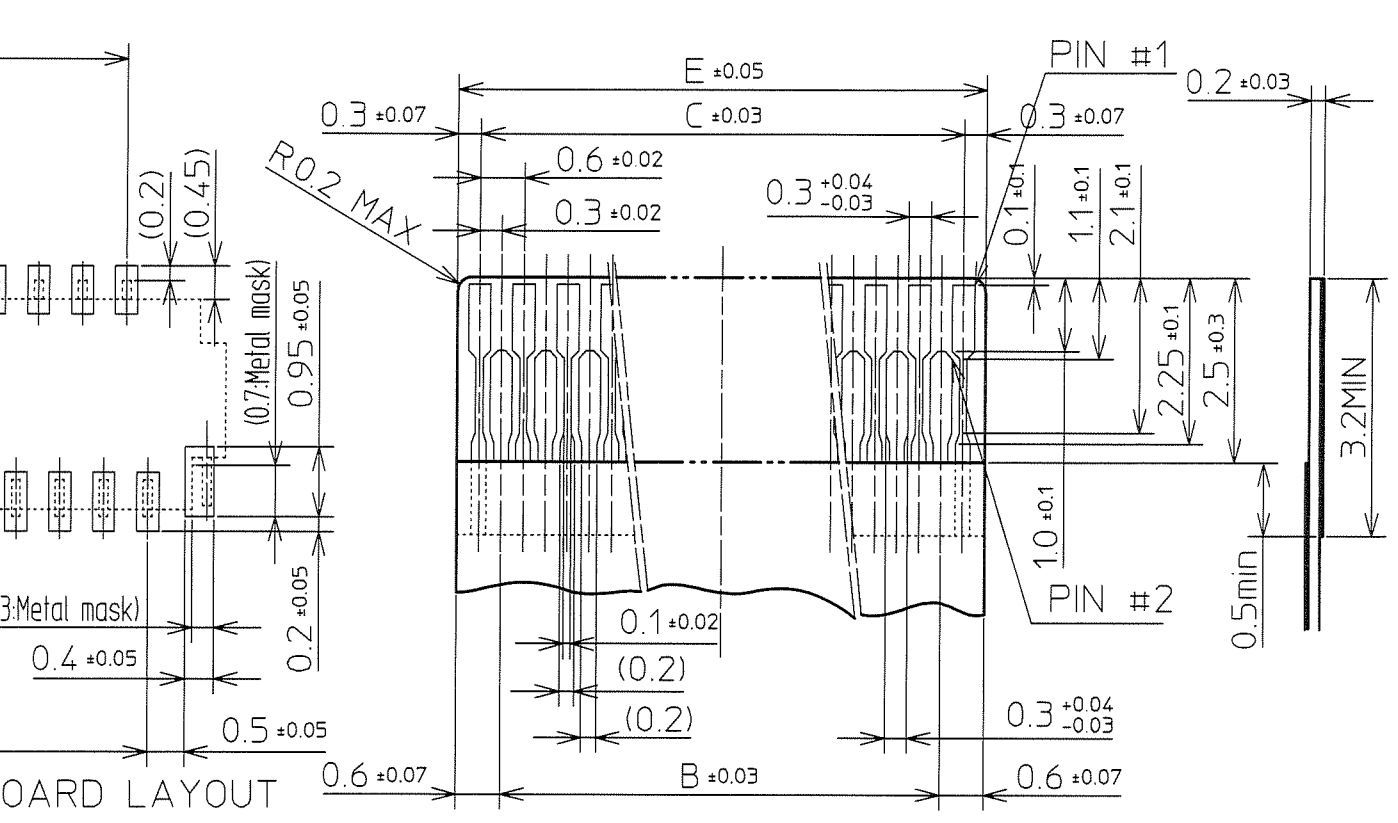
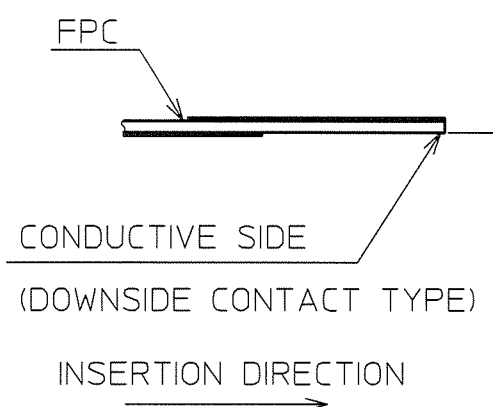
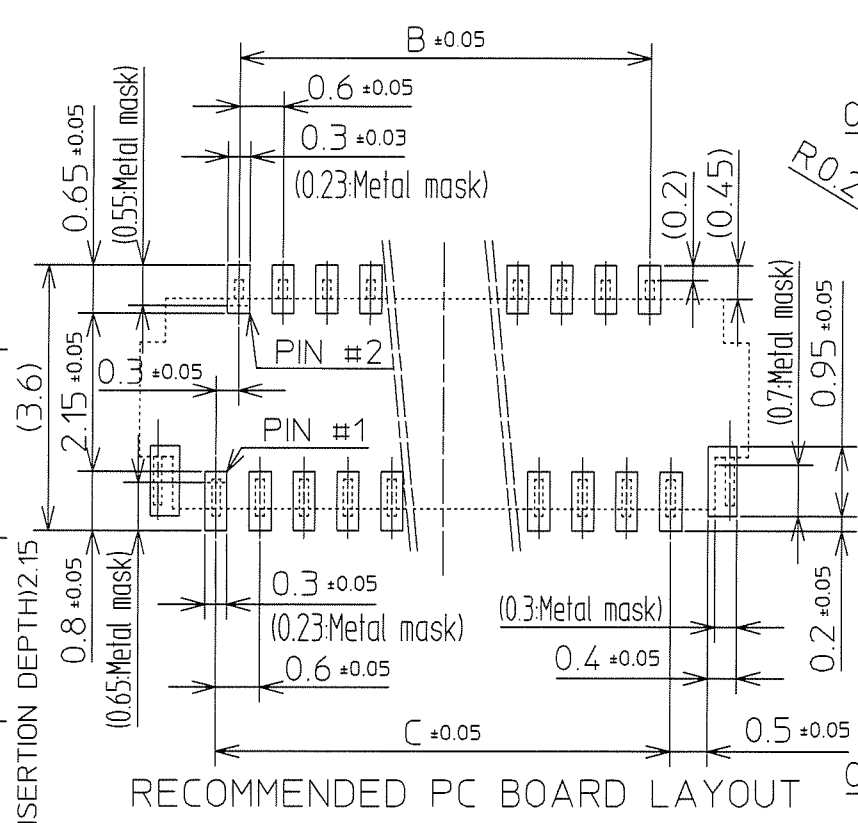


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PRODUCT NO.
10061122-**-121LF



NOTE
1.MATERIAL
1)HOUSING:THERMOPLASTIC RESIN,UL94V-0,NATURAL
2)ACTUATOR:THERMOPLASTIC RESIN,UL94V-0,BLACK
3)CONTACT:COPPER ALLOY
4)FIXING TAB:COPPER ALLOY
2.FINISH
1)CONTACT:ALL OVER Ni (WITH Ni BARRIER) (CONTACT AREA)Au (SOLDER TAIL AREA)Au
2)FIXING TAB:ALL OVER Ni Sn PLATING
3.CO-PLANARITY: 0.08MAX
4.THICKNESS OF A METAL MASK:0.1mm
5.FPC
ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.
6.PRODUCT
RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-**-2210ELF(YLL-UPPER CONTACT TYPE)
7.OTHER
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008

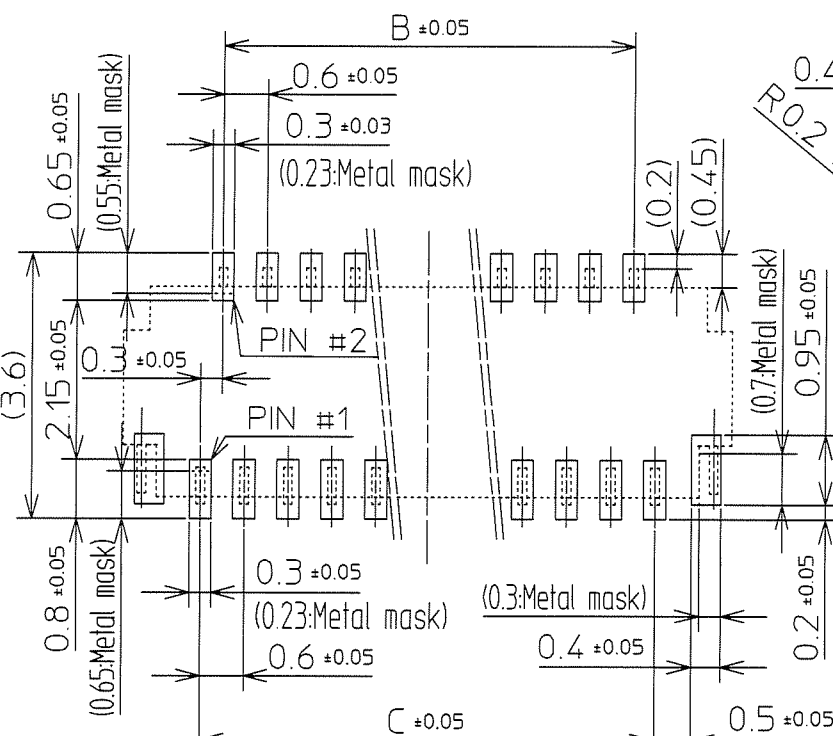
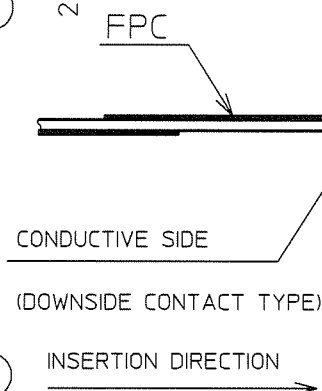
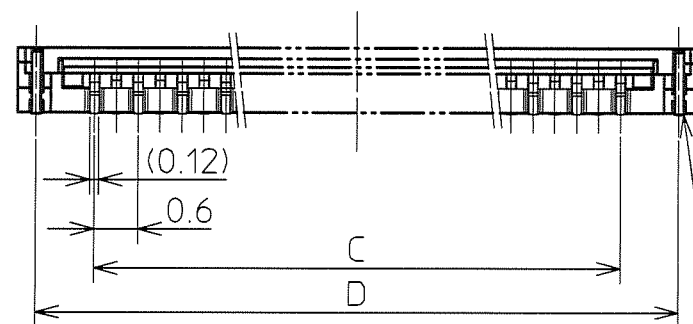
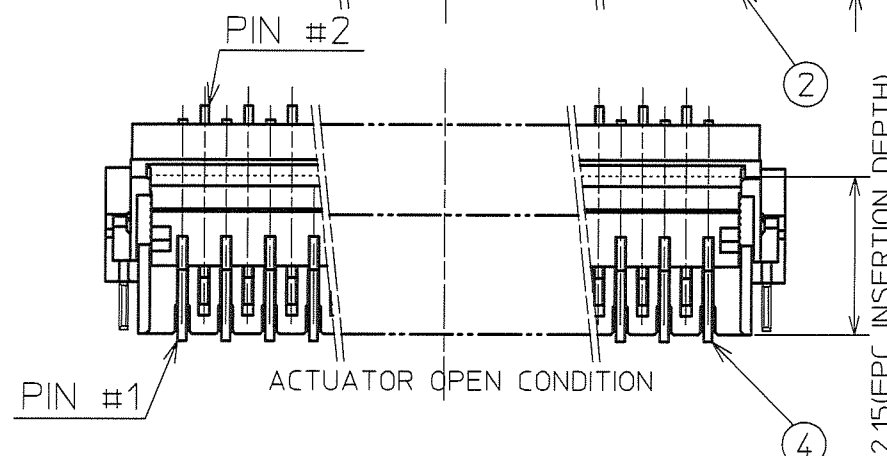
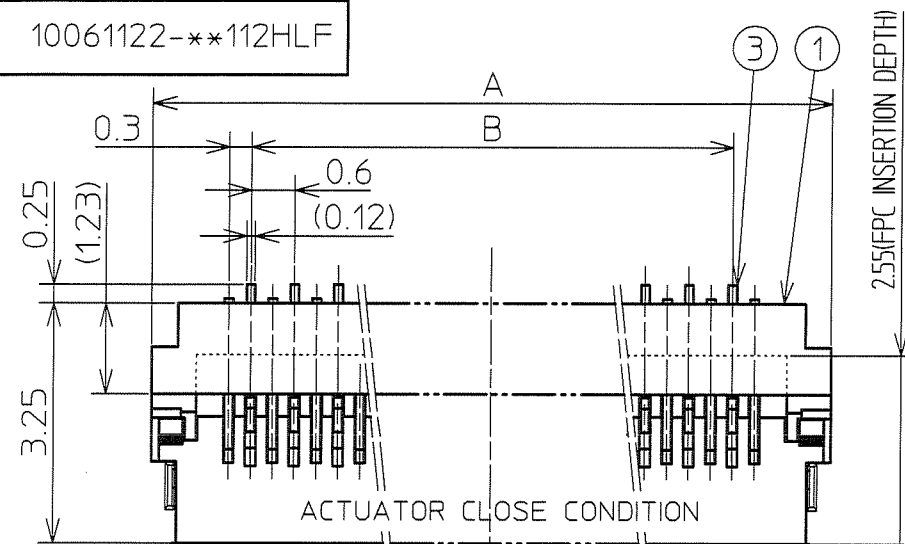


P/N	A	B	C	D	E
10061122-15121LF	6.3	3.6	4.2	5.8	4.8
10061122-21121LF	8.1	5.4	6.0	7.6	6.6
10061122-23121LF	8.7	6.0	6.6	8.2	7.2
10061122-25121LF	9.3	6.6	7.2	8.8	7.8
10061122-33121LF	11.7	9.0	9.6	11.2	10.2
10061122-35121LF	12.3	9.6	10.2	11.8	10.8
10061122-37121LF	12.9	10.2	10.8	12.4	11.4
10061122-39121LF	13.5	10.8	11.4	13.0	12.0
10061122-41121LF	14.1	11.4	12.0	13.6	12.6
10061122-43121LF	14.7	12.0	12.6	14.2	13.2
10061122-45121LF	15.3	12.6	13.2	14.8	13.8

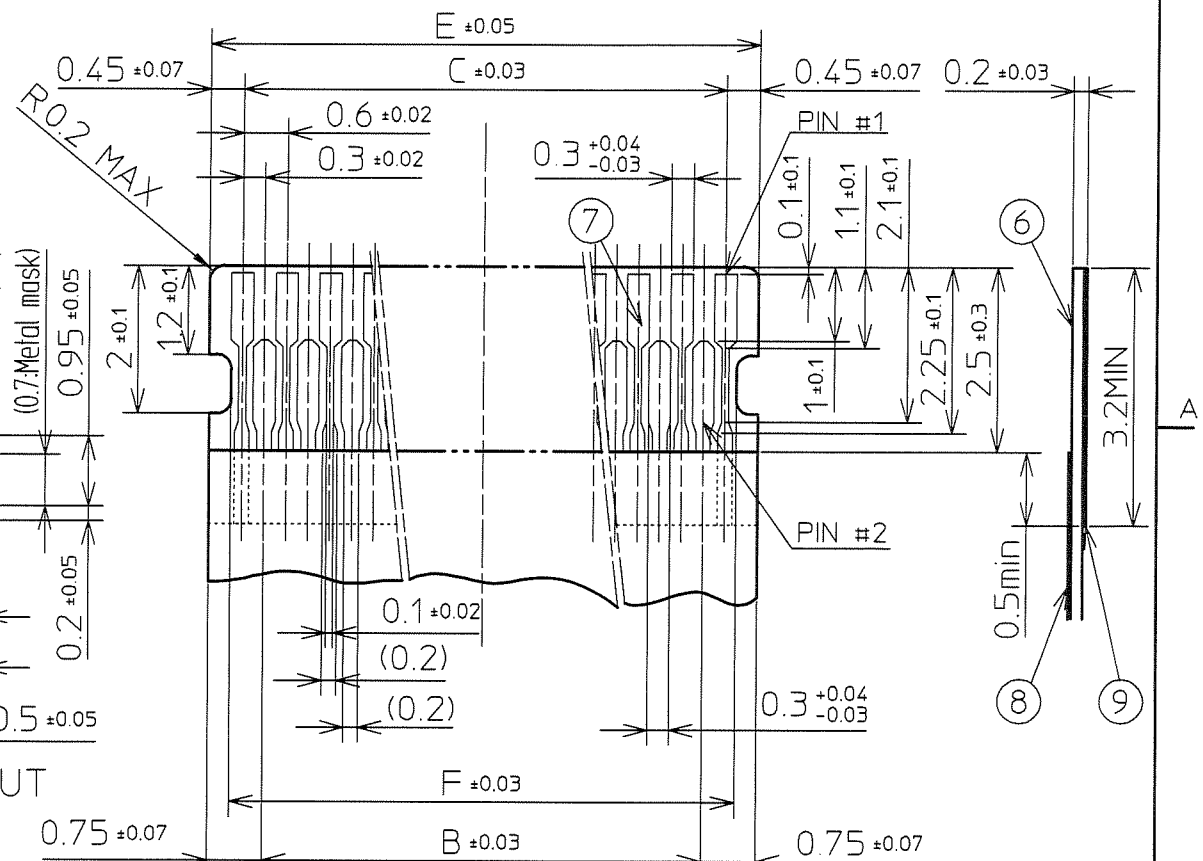
mat'l. code					surface		tolerance		projection		product family				CODE					
					ISO 1302		ISO 406 ISO 1101				587F				JP					
description					tolerances unless otherwise specified					title										
					angles		linear		MM		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE									
E REVISED					J10-0185		T.I		2010-7-6		scale									
D REVISED					J10-0073		T.I		2010-5-17		dr		2010-07-06		dwg no		sheet of		size	
C REVISED					J08-0430		K.O		2008-11-10		engr		T.ISHISHITA		10061122		3 of 37		A3	
B REVISED					J08-0189		K.O		2008-4-28		chr		Z. Kameda		2010-07-06					
A RELEASED					J07-0399		K.O		28/Sep/07		appd		M. Kimura		Jul 6/10					
sheet		revision																Rev.		
index		sheet																E		

PRODUCT NO.

10061122-**-112HLF



RECOMMENDED PC BOARD LAYOUT



RECOMMENDED FPC CONFIGURATION

PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

CONNECTOR

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

n:NO OF CONTACT

NOTE

1.CO-PLANARITY:0.08mmMAX

2.THICKNESS OF A METAL MASK:0.1mm

3.FPC

Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)

5.OTHER

This product meets European Union Directives and other country regulation as described in GS-22-008

P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

*For the corresponding position, please make an inquire to sales person in our company.

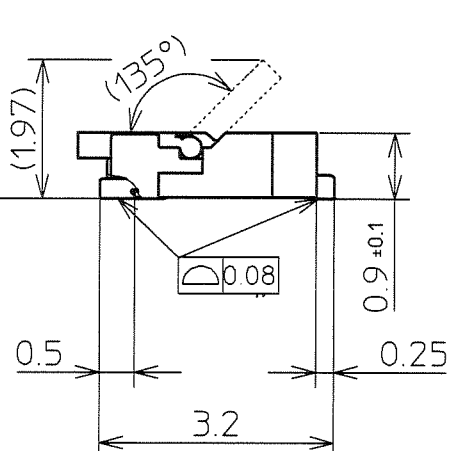
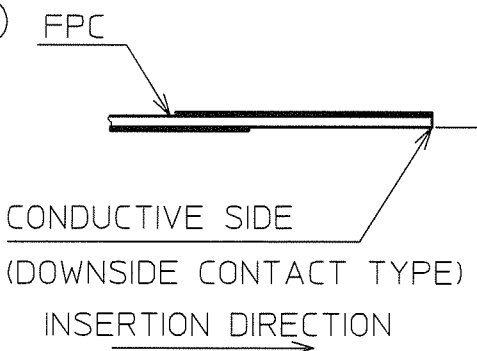
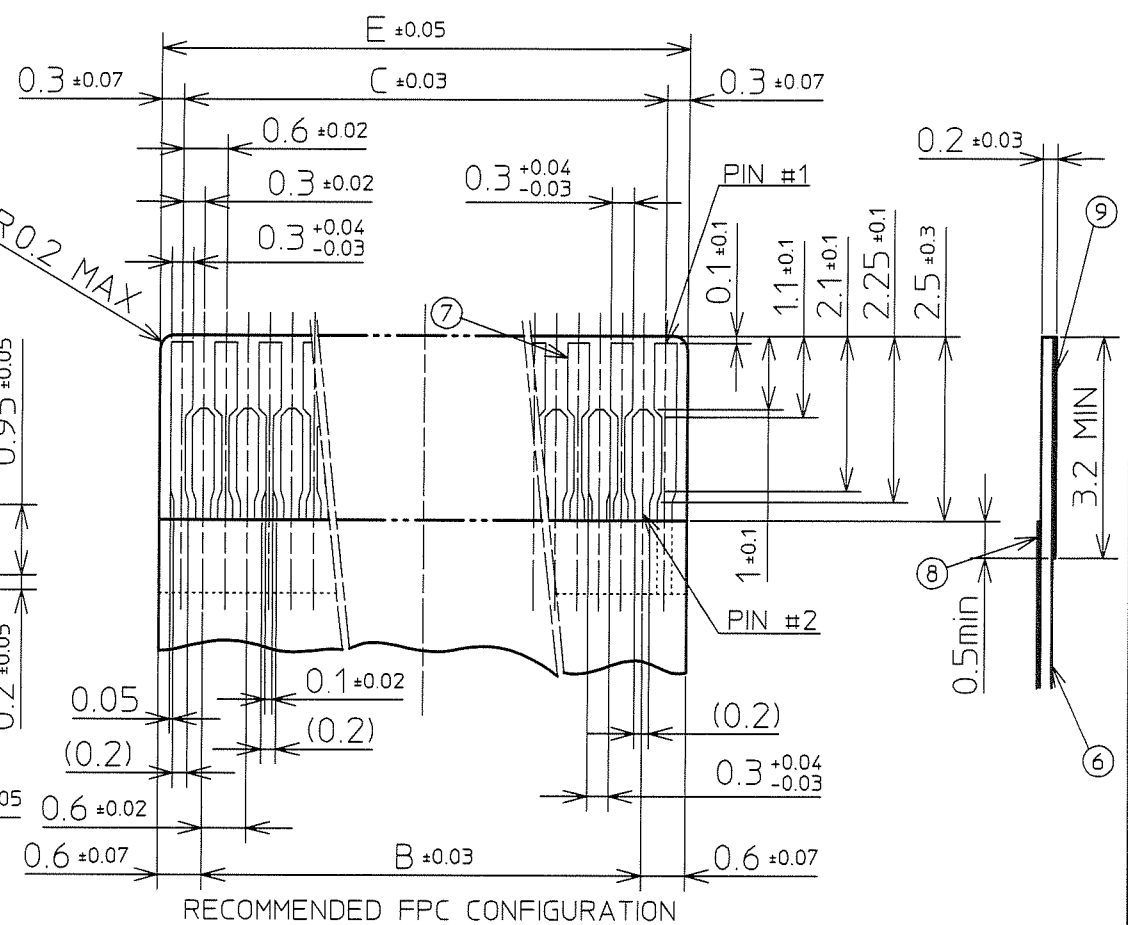
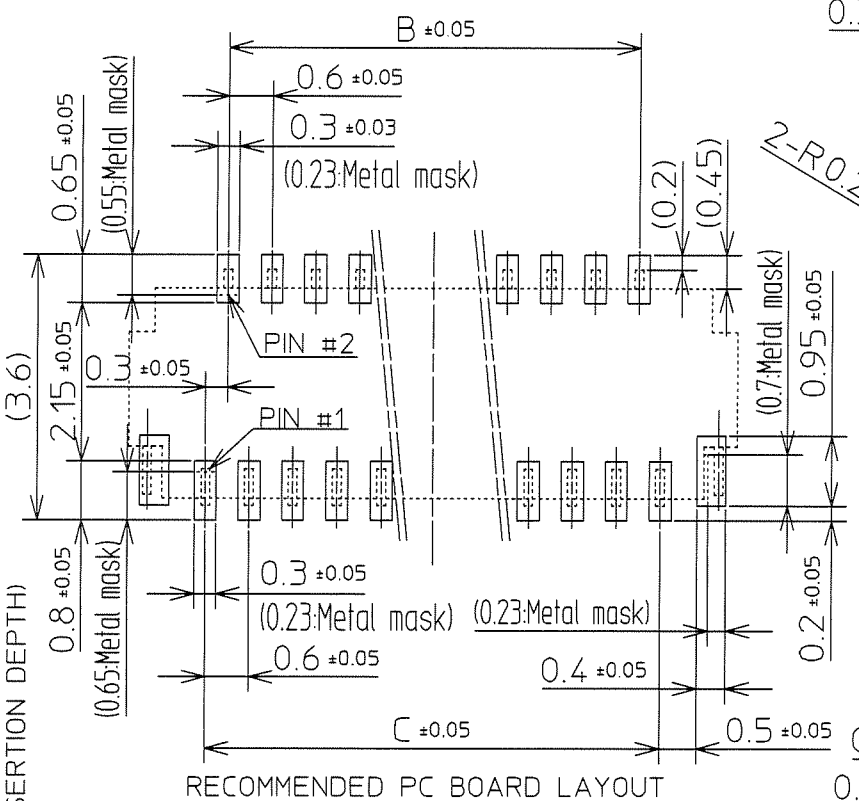
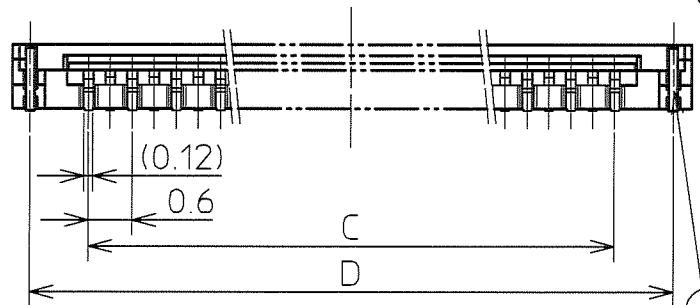
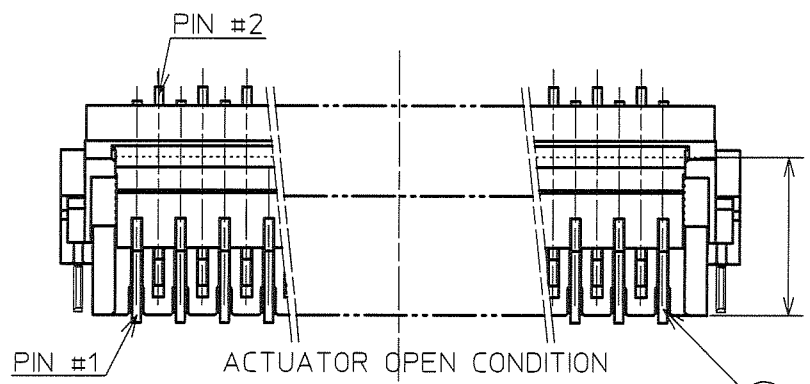
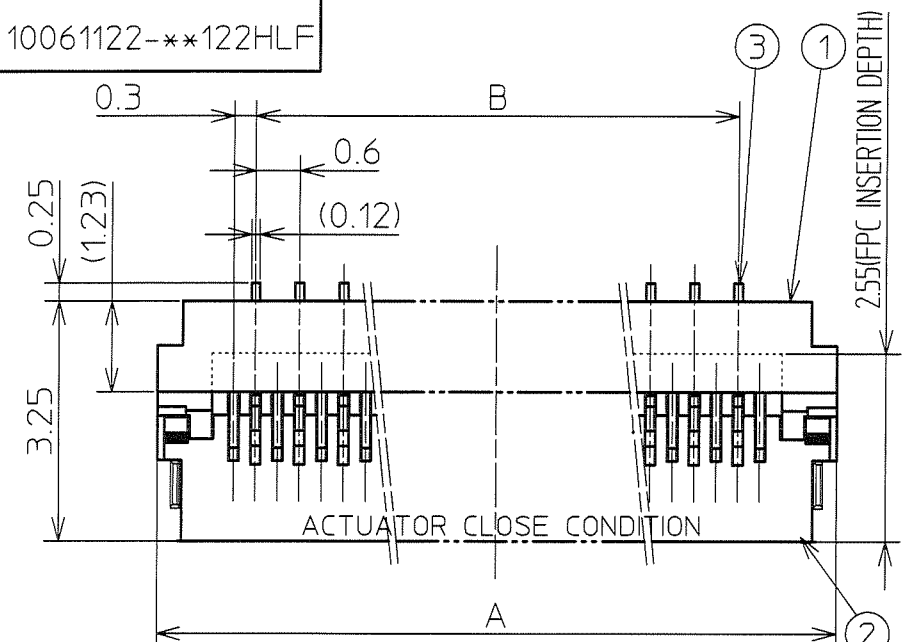
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ltr description	ecn no	dr date	tolerances unless otherwise specified	title	
A Released	J10-0185	T.I	2010-7-6	0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE	
			angles linear	scale	
			±2'		
			dr engr T.ISHISHITA	2010-07-06	
			chr Y. Kamada	2010-07-06	
			appd M. Kato	Jul 6/10	
sheet index	revision sheet			dwg no 10061122	sheet of 4 of 7
				type Product Customer	Drawing
					Rev. A



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PRODUCT NO
10061122-**122HLF



PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12 μm, Au 0.05~0.15 μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n: NO OF CONTACT

P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

*For the corresponding position, please make an inquire to sales person in our company.

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Su

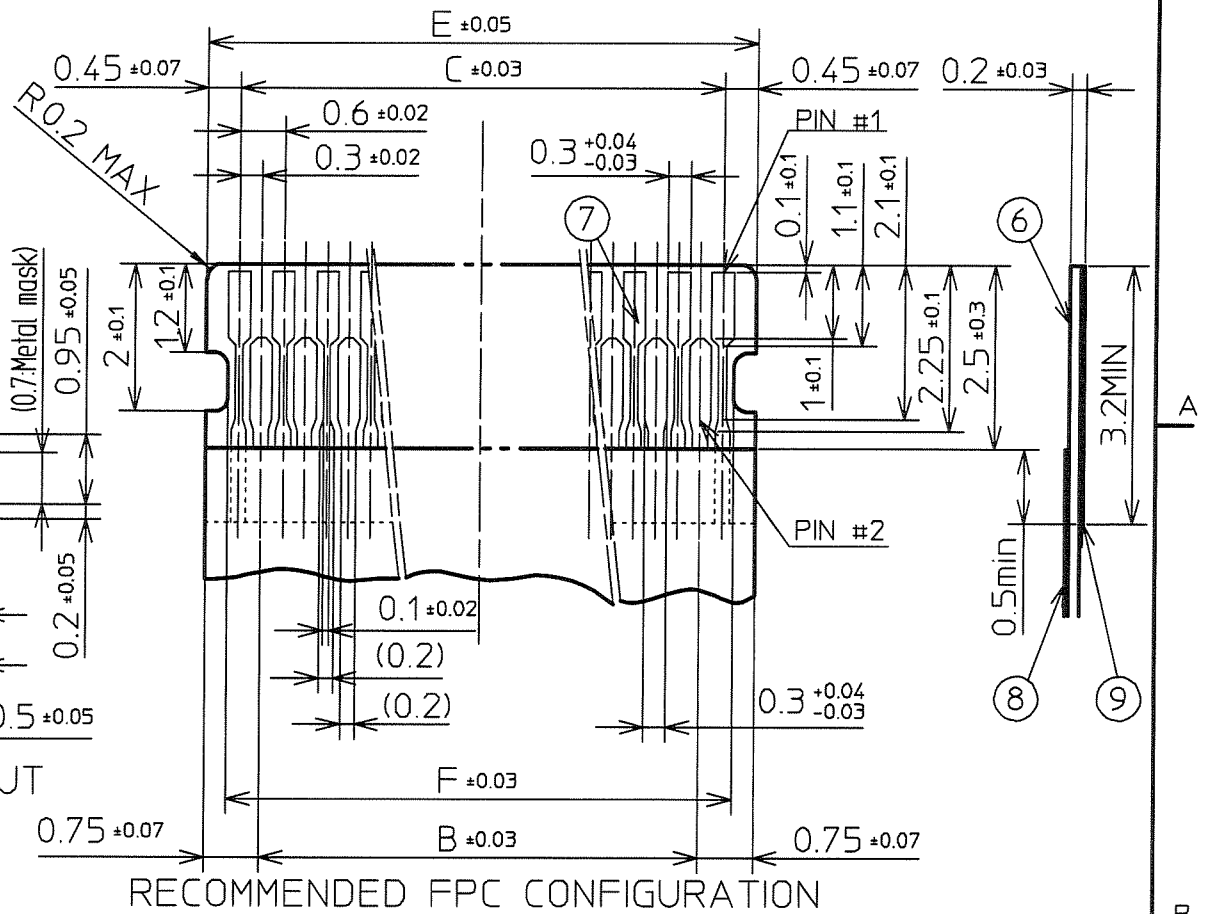
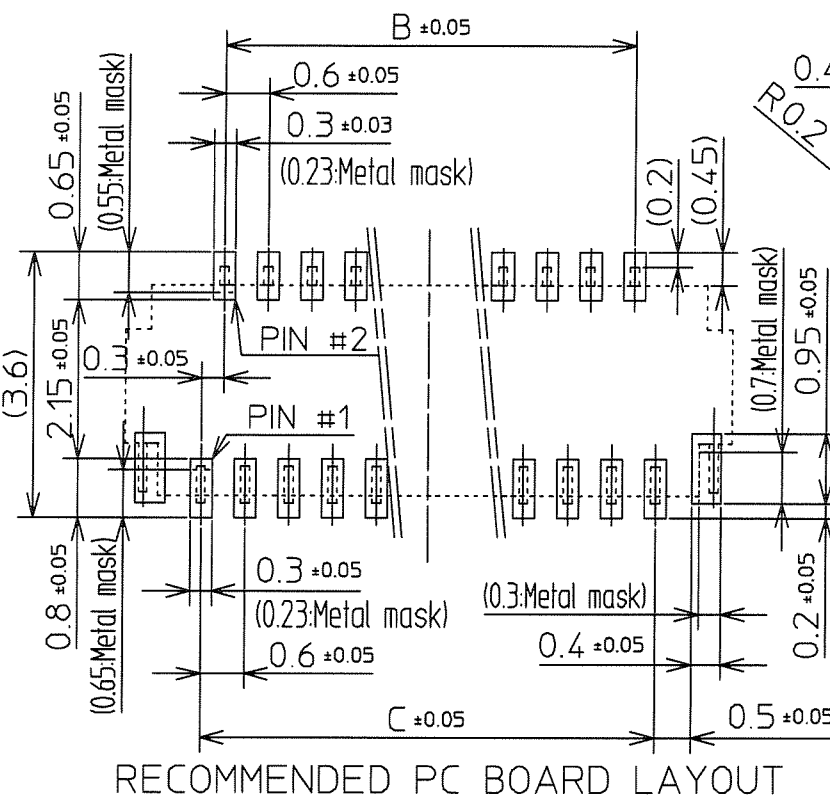
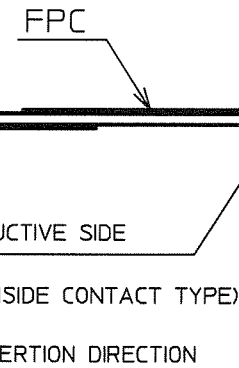
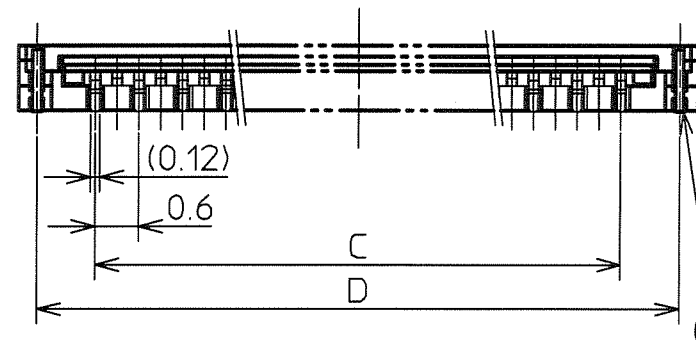
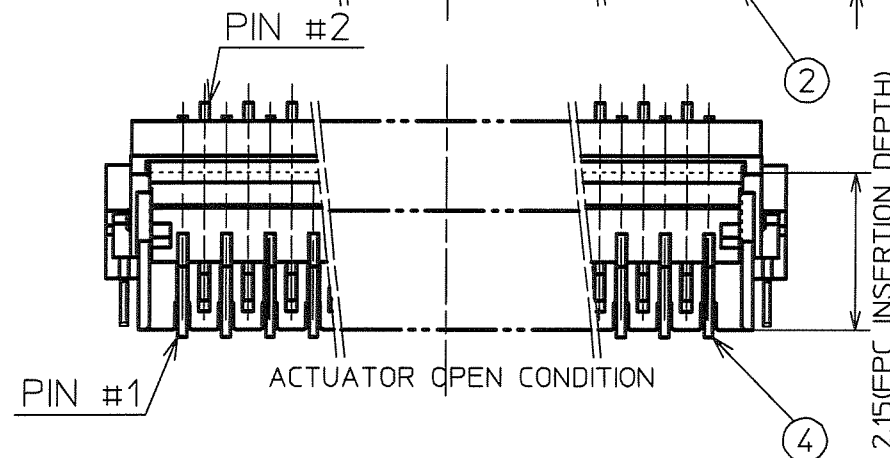
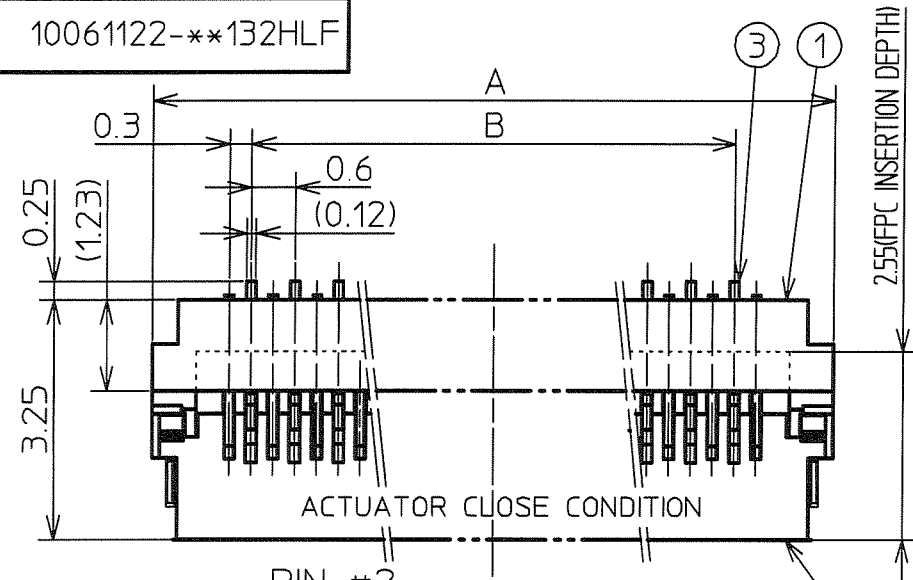
n: NO OF CONTACT

NOTE
1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC
Adhesive method of supporting tape shall be heat crimping method
and thermosetting adhesive material shall be used.
4.PRODUCT
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)
5.OTHER
This product meets European Union Directives and other country reguation
as described in GS-22-008

mat'l. code				surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection MM		product family 587F (YLL-D)		CODE JP	
lfr description				ecn no		dr date		angles linear		title 0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE			
A Released				J10-0185		T.J. 2010-7-6		± 2°					
								dr		dwg no		sheet of	
								engr T.ISHISHITA		2010-07-06		size	
								chr Y. Kameda		2010-07-06		10061122 5 of 7 A3	
								appd M. Kameda		Jul 6/10		type Product Customer Drawing	
sheet index				revision sheet								Rev. A	

PRODUCT NO.

10061122-**132HLF



FPC

PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-27132HLF	9.9	7.2	7.8	9.4	8.7	8.1
10061122-29132HLF	10.5	7.8	8.4	10.0	9.3	8.7
10061122-33132HLF	11.7	9.0	9.6	11.2	10.5	9.9
10061122-35132HLF	12.3	9.6	10.2	11.8	11.1	10.5
10061122-39132HLF	13.5	10.8	11.4	13.0	12.3	11.7
10061122-41132HLF	14.1	11.4	12.0	13.6	12.9	12.3

*For the corresponding position, please make an inquire to sales person in our company.

CONNECTOR

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

n:NO OF CONTACT

NOTE

1.CO-PLANARITY:0.08mmMAX

2.THICKNESS OF A METAL MASK:0.1mm

3.FPC

Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

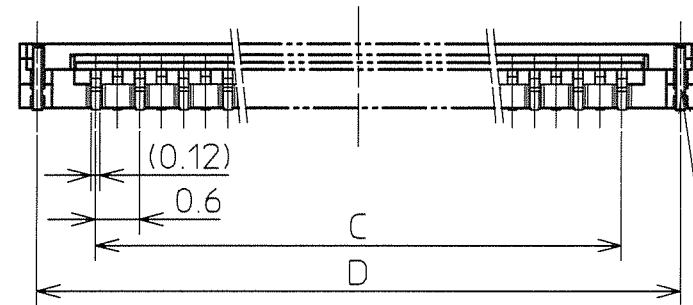
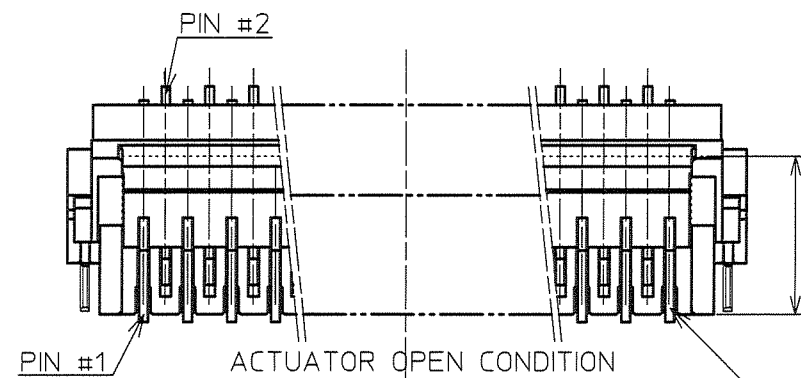
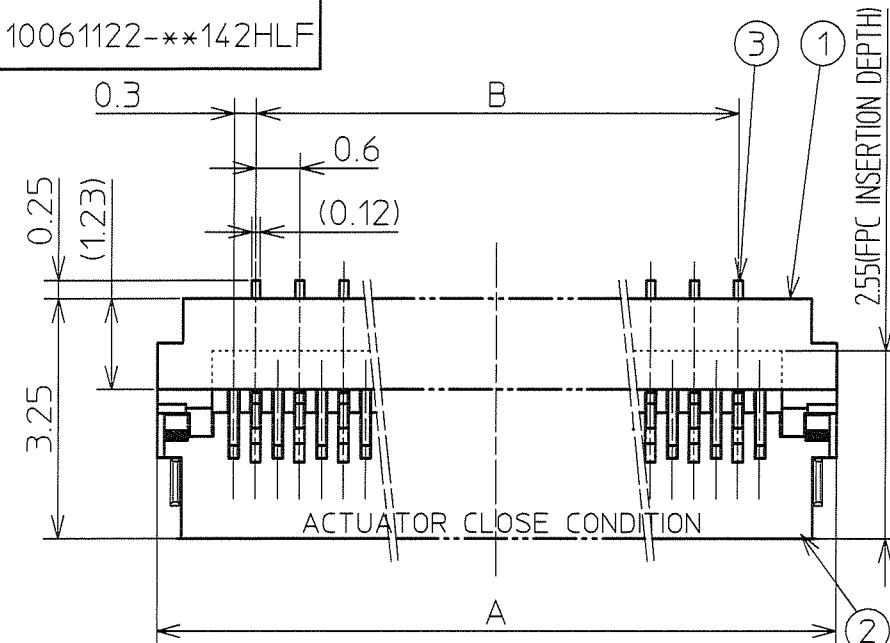
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)

5.OTHER

This product meets European Union Directives and other country regulation as described in GS-22-008

mat'l. code					surface		tolerance		projection	product family		CODE	
					ISO 1302 ✓		ISO 406 ISO 1101			587F (YLL-D)			JP
lir	description	ecn no	dr	date	tolerances unless otherwise specified					title			
A	Released	J10-0185	T.I	2010-7-6	angles	linear	± 0.2			MM	0.3mm PITCH FPC CONNECTOR		
B	Revised	J10-0268	T.I	2010-10-12					DOWN CONTACT TYPE				
					± 2'				scale				
					dr	TISHISHITA		2010-10-12		dwg no		sheet of	size
					engr					10061122		6 of 7	A3
					chr	Z. Zangala		2010-10-12					
					appd	M. M. M. M.		00114/10					
sheet	revision								type	Product	Customer	Drawing	Rev.
index	sheet												B

10061122-**-142HLF



	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:AU SOLDER TAIL AREA:AU
4	CONTACT B	COPPER ALLOY	(n+1)/2	
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

NOTE
1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC

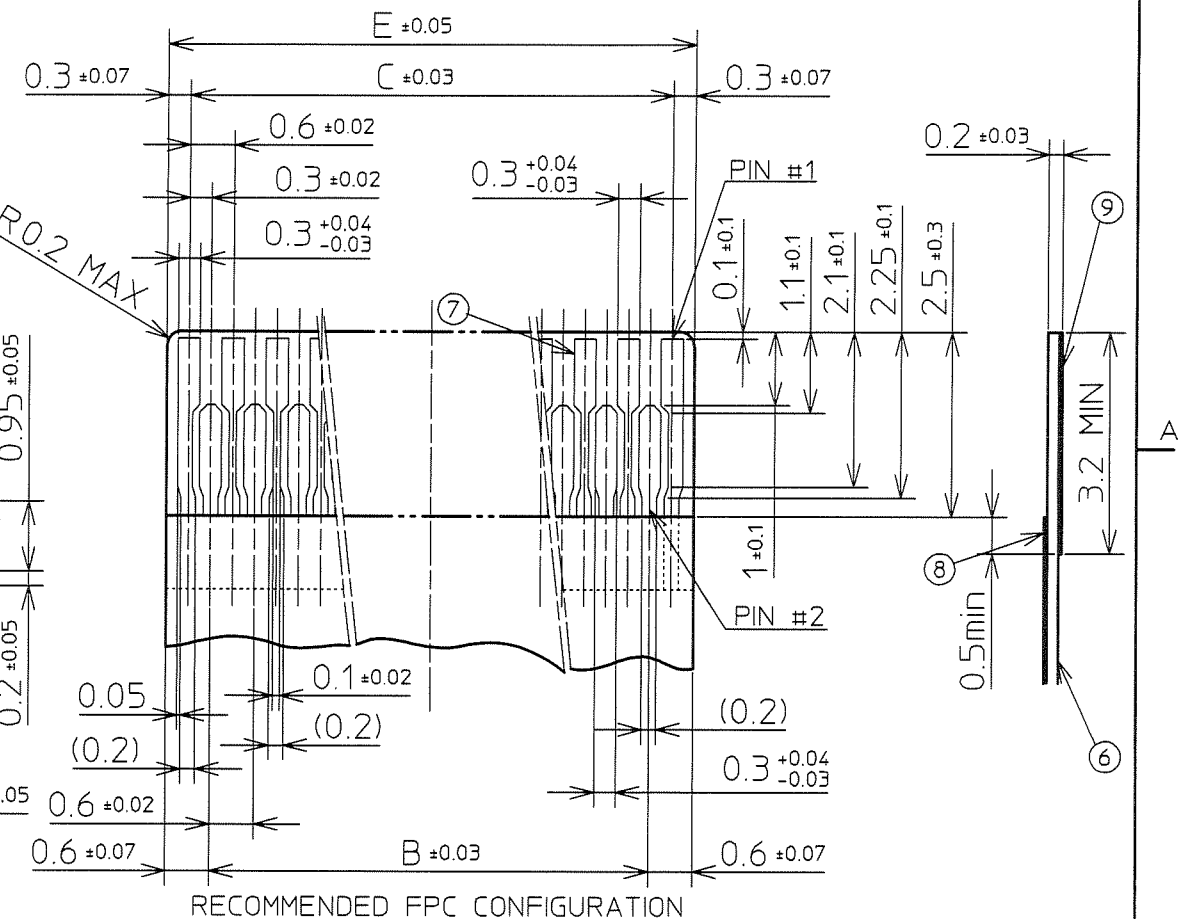
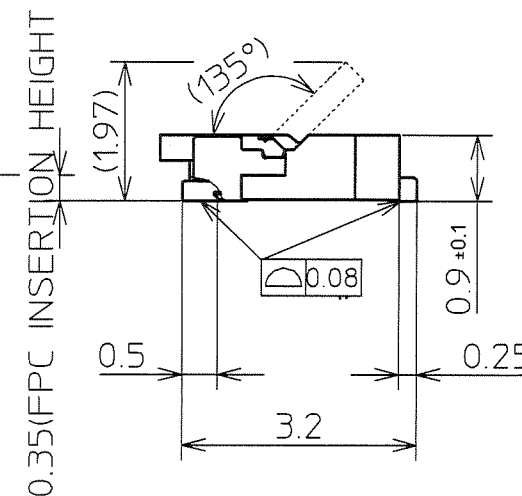
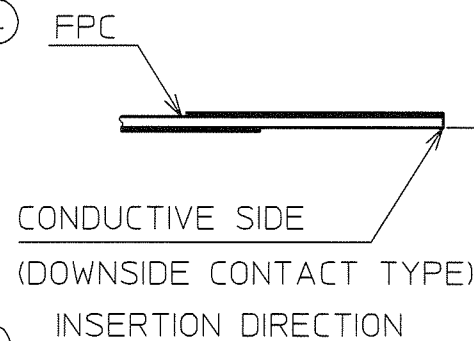
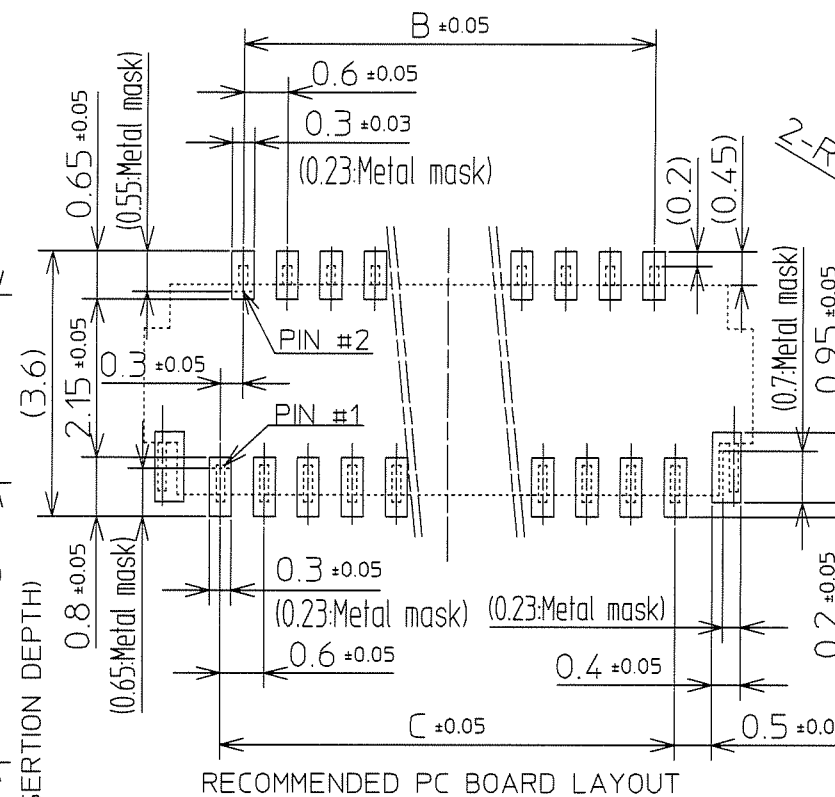
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)

5.OTHER

This product meets European Union Directives and other country regulation as described in GS-22-008



FPC				
	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12 μm , Au 0.05~0.15 μm
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)				CODE JP			
ltr	description		ecn no	dr	date	tolerances unless otherwise specified					title 0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE							
A	Released		J10-0185	T.I	2010-7-6	angles		linear	± 0.2								MM 	
						± 2°												
						dr		T.ISHISHITA		2010-07-06				dwg no		sheet of		size
						engr								10061122		7 of 7		A3
						chr		Y. Kameoka		2010-07-06				type		Product Customer		Drawing
						appd				Jul 6/10								Rev. A
sheet index		revision sheet																